## Device Material Content

**Package Code:** CB121  
**Size (mm):** 6 x 6  
**Lead pitch (mm):** 0.5  
**MSL:** 3  
**Reflow max (°C):** 260

### Die
- **% of Total Pkg. Wt.:** 6.32%  
- **Weight (g):** 0.0036  
- **% of Total Pkg. Wt.:** 6.32%  
- **Weight (g):** 0.0036  
- **Substance:** Silicon chip  
- **CAS #:** 7440-21-3  
- **% of Subst.:** 100.00%  
- **Notes / Assumptions:** Die size: 2.49 x 2.51 mm

### Mold Compound
- **% of Total Pkg. Wt.:** 61.19%  
- **Weight (g):** 0.0349  
- **% of Total Pkg. Wt.:**   
- **Weight (g):**  
- **Substance:** Epoxy Resin  
- **CAS #:** -  
- **% of Subst.:** 7.00%  
- **Notes / Assumptions:** Mold Compound: Kyocera KE-G1250 series

### D/A Tape
- **% of Total Pkg. Wt.:** 0.31%  
- **Weight (g):** 0.0018  
- **% of Total Pkg. Wt.:**  
- **Weight (g):**  
- **Substance:** Epoxy Resin  
- **CAS #:** -  
- **% of Subst.:** 15.00%  
- **Notes / Assumptions:** Die attach: Hitachi FH-900 HR-9004 series

### Wire
- **% of Total Pkg. Wt.:** 1.92%  
- **Weight (g):** 0.0011  
- **% of Total Pkg. Wt.:**  
- **Weight (g):**  
- **Substance:** Copper  
- **CAS #:** 7440-50-8  
- **% of Subst.:** 98.50%  
- **Notes / Assumptions:** 0.8 mil diameter; 1 wire per solder ball

### Solder Balls
- **% of Total Pkg. Wt.:** 1.82%  
- **Weight (g):** 0.00104  
- **% of Total Pkg. Wt.:**  
- **Weight (g):**  
- **Substance:** Tin (Sn)  
- **CAS #:** 7440-31-5  
- **% of Subst.:** 98.50%  
- **Notes / Assumptions:** SAC105

### Substrate
- **% of Total Pkg. Wt.:** 18.48%  
- **Weight (g):** 0.0105  
- **% of Total Pkg. Wt.:**  
- **Weight (g):**  
- **Substance:** BT Resin  
- **CAS #:** 65997-17-3  
- **% of Subst.:** 68.00%  
- **Notes / Assumptions:** BT Resin CCL-HL832NX-A

### Foil
- **% of Total Pkg. Wt.:** 4.11%  
- **Weight (g):** 0.0023  
- **% of Total Pkg. Wt.:**  
- **Weight (g):**  
- **Substance:** Copper  
- **CAS #:** 7440-50-8  
- **% of Subst.:** 74.07%  
- **Notes / Assumptions:**

### Solder Mask
- **% of Total Pkg. Wt.:** 5.84%  
- **Weight (g):** 0.0033  
- **% of Total Pkg. Wt.:**  
- **Weight (g):**  
- **Substance:** Quartz  
- **CAS #:** 14818-60-7  
- **% of Subst.:** 56.20%  
- **Notes / Assumptions:** Solder mask PSR4008 AUS 308

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